

Growth of Ru–SiO₂ underlayer for Co₇₂Pt₂₈–SiO₂ nanocomposite films

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The effects of sputter growth conditions of Ru–SiO₂ underlayer (hereafter referred as Ru_i layer) on the microstructure of this layer were studied. The effects of growth conditions of the Ru_i layer on the microstructure and magnetic properties of the Co₇₂Pt₂₈–SiO₂ top layer were further investigated. Results show that increasing SiO₂ content in the Ru_i layer deteriorates slightly the texture of Ru grains in this layer generally. The high-pressure (1.3 Pa) deposition can better protect the texture of Ru than low-pressure (0.4 Pa) deposition with SiO₂ addition. Furthermore, high-pressure deposition of Ru_i layer with low SiO₂ content produces better texture of Co₇₂Pt₂₈ than

low pressure. The sizes of Ru grains and Co₇₂Pt₂₈ grains decrease with increasing SiO₂ content. A high-pressure deposition of Ru_i layer further reduces the grain size of Co₇₂Pt₂₈. Both the coercivity and the remanence ratio of Co₇₂Pt₂₈ layer decrease when SiO₂ content in the Ru_i layer exceeds 10 vol.%. High-pressure deposition of Ru_i layer results in a higher coercivity and remanence ratio of Co₇₂Pt₂₈ layer than those with low-pressure depositions. The above results show that the grain size of Co₇₂Pt₂₈ can be reduced without sacrificing its magnetic properties at small SiO₂ content.

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1 Introduction In recent years, the urgent need to engineer the magnetic nanostructures at nanoscale level has led to a growing interest in the preparation, investigation and control of the properties of the magnetic nanoparticles and thin films [1]. One of the major challenges in further increasing the areal density of perpendicular magnetic recording media is in reducing the grain size and improving the signal to noise ratio by minimizing transition noise [2]. Efforts have been made to reduce grain size by adding oxide-based materials into the magnetic layer [3] or by depositing the magnetic layer in an argon and oxygen environment [4]. However, too much oxide in the magnetic layer would reduce its magnetic anisotropy, leading to increased thermal instability due to the superparamagnetic effect. An alternative approach is to reduce the grain size of the intermediate layer and hence, the grain size of the magnetic layer. The addition of synthetic nucleation layers [5], RuCr-oxide underlayer [6], NiAl underlayer [7] and Ar-etched Ru underlayer [8, 9] have been reported to be able to decrease the grain size of the magnetic layer to below 6 nm. However, a deteriorated texture or reduction of the nucleation field of the magnetic layer was also observed. Recently, it was

reported that doping oxide into the Ru underlayer could reduce the grain size of magnetic layer [10]. The reduction of grain size was based on a large volume fraction of oxide addition into the Ru underlayer, which deteriorated the texture of the latter. The growth conditions of the Ru-oxide underlayer was not reported in detail. Moreover, the texture information of the CoPt layer, which was important for evaluation of the media qualities, was not obtained. A systematic understanding of the effects of growth conditions on the microstructure of the nano-sized Ru grains, and its effects on the growth of CoPt grains was both scientifically interesting and technologically important. In this paper, SiO₂ was doped into the Ru intermediate layer to reduce the grain size of the Co₇₂Pt₂₈–SiO₂ magnetic layer. The effects of sputtering power, pressure and SiO₂ volume fraction of Ru–SiO₂ underlayer on the microstructure of this layer were studied. The effects of growth conditions of the Ru–SiO₂ layer on the microstructure and magnetic properties of Co₇₂Pt₂₈–SiO₂ layer were further investigated.

2 Experimental Granular films of Co₇₂Pt₂₈–SiO₂(15 nm)/Ru–SiO₂(10 nm)/Ru_b(bottom Ru, 15 nm)/Ta

(4 nm)/glass were deposited at room temperature by magnetron sputtering. The base pressure of sputtering was lower than 5×10^{-6} Pa. The Ta layer and Ru_b layer were deposited at 0.4 Pa. The Ru–SiO₂ (hereafter referred to as Ru_t) layer was deposited at 0.4 Pa and 1.3 Pa argon pressures respectively. The Co₇₂Pt₂₈, Ru, Ta, and SiO₂ targets were used for the sputtering. DC and AC sputtering were used for the metal and SiO₂ targets respectively. The volume fraction of SiO₂ (hereafter referred as V_{SiO_2}), adjusted by changing the sputtering time of SiO₂ relative to that of Ru, was varied from 0 to 20% in the Ru_t underlayer. The composition and thickness of the Co₇₂Pt₂₈–SiO₂ layer were kept constant in all samples. The crystallographic information of the films were investigated using Philips X'Pert X-ray diffractometer (XRD) with Cu K α_1 radiation (source wavelength is 1.5406 Å). The microstructures of the films were investigated using JEOL-2010 transmission electron microscope (TEM). Magnetic properties of the media were measured using the vibrating sample magnetometer (VSM, Lakeshore 7407) under maximum applied field of 1.2 T.

3 Results and discussion

3.1 Microstructures of Ru_t layer Figure 1 show the Ru_b/Ru_t double layer XRD θ – 2θ spectrum with Ru_t layer deposited at different deposition pressure, power and V_{SiO_2} . The Ru_t layer was deposited at low pressure (0.4 Pa) and high pressure (1.3 Pa) with powers of low power (15 W) and high power (50 W) respectively. Figure 1(a) shows the different deposition conditions had not changed the lattice constant c of Ru. The exceptions were for films with Ru_t layer deposited at 15 W and 1.3 Pa, which had a larger lattice constant c of Ru than other films. This larger lattice constant indicated that there was out-of-plane tensile strain in the Ru grains. This tensile strain should be due to the reduced surface curvature of the Ru grains grown at low power and high pressure [11, 12].

The XRD θ – 2θ mode of operation scans through reciprocal space in a direction normal to the substrate surface and thus measure the intensity along such a trajectory in k -space, while a rocking curve scans through reciprocal space in a direction parallel to the substrate surface [13, 14]. Hence, the integrated intensity of the symmetric film reflections for a highly textured film in the θ – 2θ mode should be proportional to the film volume and inversely proportional to the rocking curve full width at half maximum (FWHM) squared [14, 15]. A compared analysis of the integrated intensity of the θ – 2θ peak and the rocking curve FWHM could give better understanding on the crystal quality of the highly textured film than that of they alone [15]. The integrated intensity of Ru(00.2) (Ru_b/Ru_t) θ – 2θ peaks (hereafter referred as I_{Ru}) were given as a function of V_{SiO_2} in Fig. 1(b) and (c). The I_{Ru} was obtained by Gauss fitting to the Ru(00.2) peaks with standard errors smaller than 1% of the I_{Ru} . The XRD measurement setups were same for all the films. Therefore, the I_{Ru} should be determined by the volume fraction and the texture of Ru in the Ru_t layer [16].

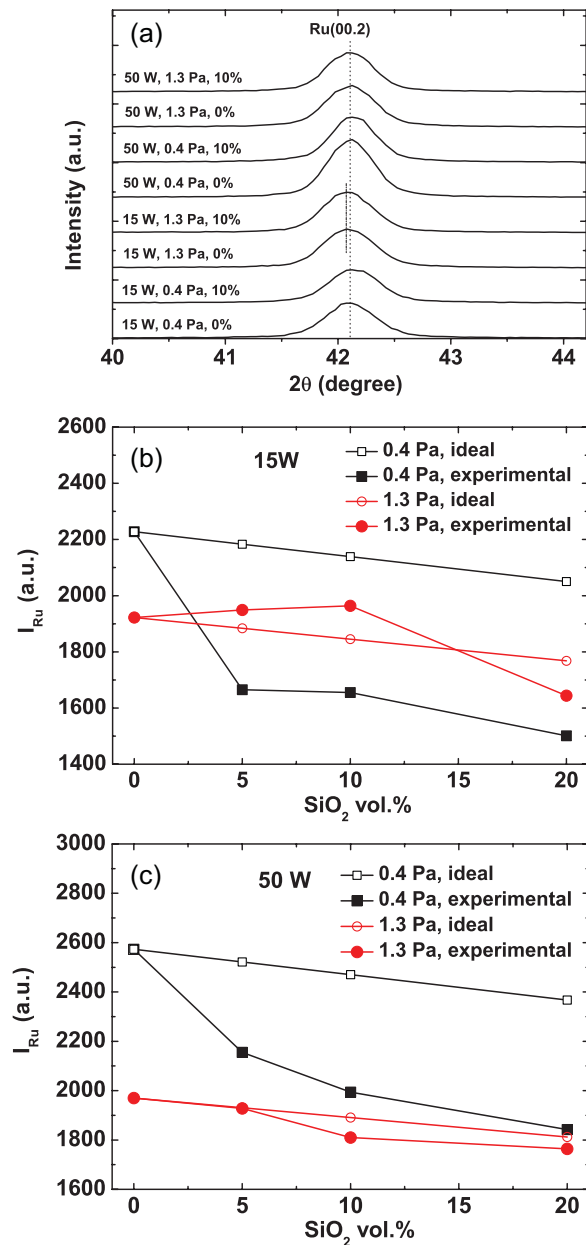


Figure 1 Plot (a) is the Ru_b/Ru_t double layer XRD θ – 2θ spectrum with Ru_t layer deposited at different deposition pressure, power and V_{SiO_2} . Plots (b) and (c) are the integrated intensity of Ru(00.2) (Ru_b/Ru_t) θ – 2θ peaks, I_{Ru} . The I_{Ru} was obtained by Gauss fitting to the Ru(00.2) peaks with standard errors smaller than 1% of the I_{Ru} . The lines were only used to guide the readers' eyes.

The total volume of the Ru and the SiO₂ in the Ru_t layer was kept constant during the experiments. We define an “ideal” case that the addition of SiO₂ into Ru_t layer only reduces the volume of Ru without changing the texture of Ru. Therefore, in the “ideal” case, I_{Ru} would decrease lineary with increasing V_{SiO_2} , as shown in Fig. 1(b) and (c). A deterioration in the texture of Ru would result in a smaller I_{Ru} than the “ideal” case, and vice versa [15]. Figure 1(b) and (c) shows generally, the experimental I_{Ru} reduced with

increasing V_{SiO_2} , and the experimental I_{Ru} were smaller than the “ideal” case. The exception was for the 15 W and 1.3 Pa depositions, where experimental I_{Ru} were slightly larger than the “ideal” case when V_{SiO_2} was small. Figure 2 shows the Ru(00.2) XRD rocking curves and the FWHM of the Ru(00.2) rocking curves a function of V_{SiO_2} . Figure 2(b) shows the SiO₂ addition led generally to an increase in FWHM. The exception was for the 15 W and 1.3 Pa depositions where FWHM decreased slightly when V_{SiO_2} was small. The results in Figs. 1 and 2 agreed qualitatively with each other, indicating a deterioration of the texture of Ru in the Ru_t layer. However, a low power and high-pressure deposition of Ru_t layer might improve the texture of Ru at small V_{SiO_2} instead. The improvement of the texture in this case might be contributed by the local tensile strain in the Ru grains as shown in Fig. 1(a).

Figure 1(b) and (c) also shows for a specific V_{SiO_2} , the combination of deposition power and deposition pressure affected the I_{Ru} greatly. The 0.4 Pa deposited Ru had larger I_{Ru} than that at 1.3 Pa depositions without SiO₂ addition, indicating a better texture at 0.4 Pa depositions. However, results changed with SiO₂ addition. For Ru_t deposited at 15 W, all the I_{Ru} at 0.4 Pa depositions were much smaller than the “ideal” values, while I_{Ru} at 1.3 Pa deposition were larger than the “ideal” values at small V_{SiO_2} . For Ru_t deposited at 50 W, all the I_{Ru} at 0.4 Pa depositions were much smaller than the “ideal” values, while I_{Ru} at 1.3 Pa deposition were only slightly smaller than the “ideal” values. The above results agreed qualitatively with the results in Fig. 2(b) where FWHM at 0.4 Pa depositions increased faster than that at 1.3 Pa depositions. These results indicated that in the case of SiO₂ addition, 1.3 Pa deposition of the Ru_t layer can better protect the texture of Ru than 0.4 Pa deposition. The total volume of the Ru_t layer was contributed by three components: the volume of Ru, the volume of SiO₂, and the volume of void grain boundaries. It was known that Ru film

tended to form a porous structure with void grain boundaries at high-pressure oblique depositions, while the low-pressure deposition tended to form a denser Ru film due to larger kinetic energy of the Ru adatoms [17]. As a result, the low-pressure deposition could produce a better texture of Ru than high-pressure deposition without SiO₂ addition, as shown in Figs 1(b), (c) and 2. However, the void grain boundaries could accommodate some of the SiO₂ added in the Ru_t layer. Therefore, the high-pressure deposition can better protect the texture of Ru than low-pressure deposition for a specific V_{SiO_2} .

Figure 3 shows the bright field TEM images of Ru_t layer deposited with different SiO₂ volume fractions under different pressures. The deposition power of Ru_t was chosen as 50 W because the high power deposition can better protect the texture of Ru at large V_{SiO_2} , as shown in Fig. 2. The average and standard deviations of the grain sizes were obtained by log–normal fitting to the grain size data (counted over randomly selected 100 pairs of grains). Figure 3(a) shows for film deposited at 0.4 Pa without SiO₂ addition, the Ru grain size was very large and grain boundaries were ill defined. This was due to the high mobility of Ru adatoms at 0.4 Pa deposition. With addition of SiO₂, isolated Ru grains were observed. The grain boundaries were deduced to be SiO₂ due to the phase separation between Ru and SiO₂. For films deposited at 1.3 Pa, isolated grains were observed even without SiO₂ addition as shown in Fig. 3(d). This was caused by the low mobility of Ru atoms and the “shadowing effect” [17] of Ru grains at 1.3 Pa deposition.

The grain boundaries were deduced to be voids. This showed that previous explanations on the deposition pressure dependent texture of Ru in Figs. 1 and 2 were justified. With the addition of SiO₂, these grain boundaries became a hybrid of voids and oxides. For both deposition pressures, the average grain size decreased with the increase of SiO₂ content. However, the grain size distributions increase with the SiO₂ content. In addition, the grain size of Ru deposited at 1.3 Pa was slightly smaller than those deposited at 0.4 Pa at the same SiO₂ addition.

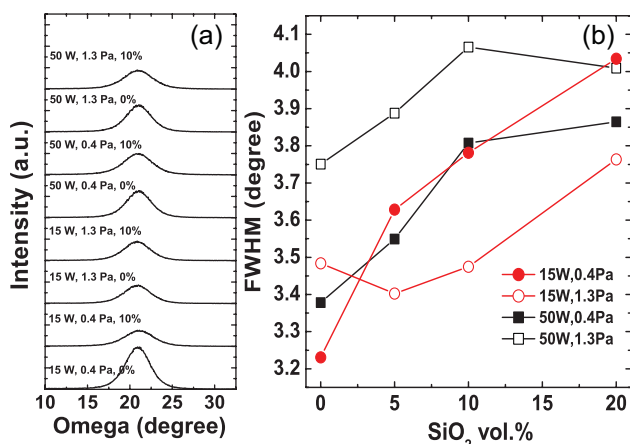


Figure 2 Plot (a) and (b) are the Ru(00.2) XRD rocking curves and the full width-at-half maximum (FWHM) of the Ru(00.2) rocking curves with Ru_t layer deposited at different deposition pressure, power and V_{SiO_2} . The lines were only used to guide the readers’ eyes.

3.2 Microstructures and magnetic properties of Co₇₂Pt₂₈–SiO₂ layer

The growth conditions of the Ru_t layer on the microstructure and magnetic properties of Co₇₂Pt₂₈–SiO₂ layer were further investigated. Figure 4(a) shows the combined XRD θ – 2θ peaks of Ru(00.2) + Co₇₂Pt₂₈(00.2) with Ru_t layer deposited at 0.4 and 1.3 Pa, and with different SiO₂ additions. The deposition power of Ru_t was 50 W. Figure 4(a) shows the peaks of Ru and Co₇₂Pt₂₈ were heavily overlapped due to the very close lattice constant c between Co₇₂Pt₂₈(00.2) and Ru(00.2). As a result, the texture information of the Co₇₂Pt₂₈ layer could not be determined directly from the XRD results. However, the changes in the integrated intensity of Co₇₂Pt₂₈(00.2) (hereafter referred as I_{CoPt}) would be mainly determined by the changes in the texture of Co₇₂Pt₂₈. This was due to the growth conditions of the Co₇₂Pt₂₈ layer were kept same during the experiments. Only the growth conditions of

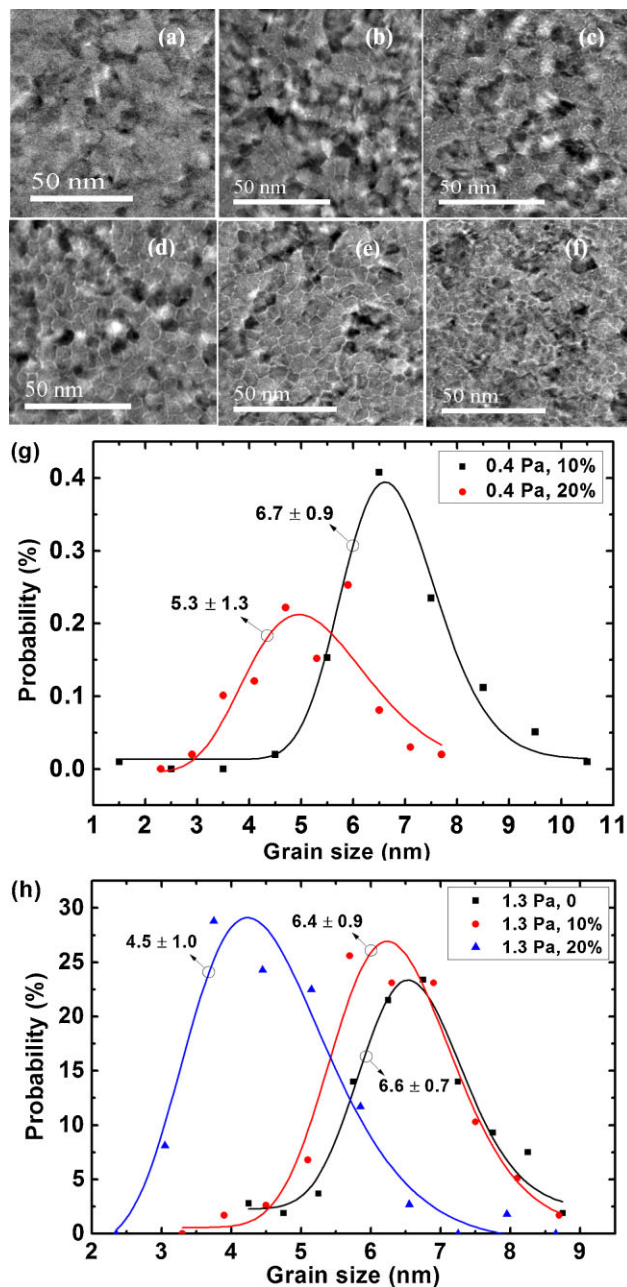


Figure 3 Planar-view TEM bright field images of Ru_t layer deposited with the SiO₂ content and pressure of (a) 0% and 0.4 Pa, (b) 10% and 0.4 Pa, (c) 20% and 0.4 Pa, (d) 0% and 1.3 Pa, (e) 10% and 1.3 Pa, and (f) 20% and 1.3 Pa. The deposition power of Ru_t layer was 50 W. Plots (g) and (h) are the corresponding grain size distributions. The grain size was center to center distance of two neighboring grains. TEM images in this figure were obtained from samples deposited on the carbon coated Cu grids.

the Ru_t underlayer were varied. Therefore, the changes in the texture of Co₇₂Pt₂₈ could be estimated from the I_{CoPt} . The I_{CoPt} in this paper was obtained by subtracting the integrated intensity of Ru(00.2) I_{Ru} from that of the corresponding combined peaks Ru(00.2) + Co₇₂Pt₂₈(00.2) (hereafter referred as $I_{\text{Ru+CoPt}}$). The $I_{\text{Ru+CoPt}}$ was obtained by Gauss

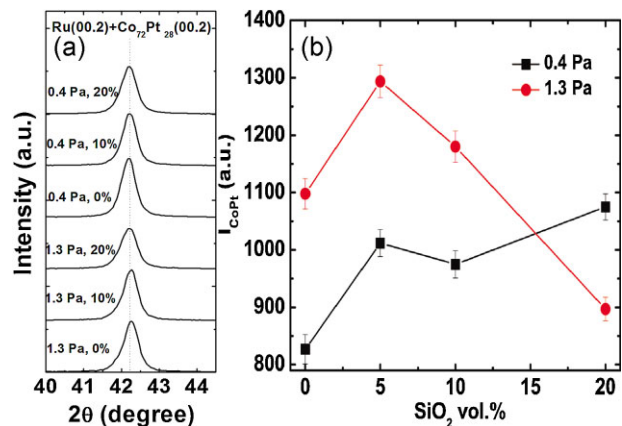


Figure 4 Plot (a) is combined XRD θ - 2θ peaks of Ru(00.2) + Co₇₂Pt₂₈(00.2) with Ru_t layer deposited at 0.4 and 1.3 Pa, and with different SiO₂ additions. The deposition power of Ru_t layer was 50 W. Plot (b) is the integrated intensities of Co₇₂Pt₂₈(00.2) peaks I_{CoPt} , which were obtained by subtracting the integrated intensities of Ru(00.2) I_{Ru} from those of the combined peaks Ru(00.2) + Co₇₂Pt₂₈(00.2) ($I_{\text{Ru+CoPt}}$). The error bars in the figure represented the standard errors of I_{CoPt} . The lines were only used to guide the readers' eyes.

fitting to the combined peaks Ru(00.2) + Co₇₂Pt₂₈(00.2) peaks with standard errors smaller than 1% of the $I_{\text{Ru+CoPt}}$. Figure 4(b) shows the I_{CoPt} as a function of SiO₂ content in Ru_t layer. From Fig. 4(b), adding 5 vol.% of SiO₂ led to a slight increase in I_{CoPt} and hence, an improved texture of Co₇₂Pt₂₈ at both 0.4 and 1.3 Pa depositions. With a further increase in SiO₂ content beyond 5 vol.%, the I_{CoPt} decreased for Ru_t deposited at 1.3 Pa, whereas there was no notable change in I_{CoPt} for Ru_t deposited at 0.4 Pa. On the other hand, the I_{CoPt} with Ru_t deposited at 1.3 Pa was much higher than that deposited at 0.4 Pa until SiO₂ content was 20 vol.%. This suggested that for a small amount of SiO₂ addition, 1.3 Pa deposition of Ru_t produced better texture of Co₇₂Pt₂₈ than that of 0.4 Pa deposition. This difference should be attributed to the difference in the grain structure of Ru_t because the texture of Ru_t at 0.4 Pa was better than that at 1.3 Pa, as shown in Fig. 2(b). However, more works are needed to understand this phenomenon.

Figure 5 shows the bright field TEM images and grain size distributions of Co₇₂Pt₂₈-SiO₂ nanocomposite films, with Ru_t deposited at 0.4 Pa (Fig. 5(a)-(c), (g) and (i)) and 1.3 Pa (Fig. 5(d)-(f), (h), and (j)). The deposition power of Ru_t layer was 50 W. The average and standard deviations of the grain sizes were obtained by log-normal fitting to the grain size data (counted over randomly selected 100 pairs of grains). Addition of SiO₂ into the Ru_t layer decreased both the grain size and size distribution of Co₇₂Pt₂₈ grains for 0.4 Pa deposited Ru_t layer. The reduction of Co₇₂Pt₂₈ grain size and size distribution was also observed for 1.3 Pa deposited Ru_t layer with vol.5% SiO₂. Further increasing SiO₂ content to vol.10% did not lead to a further reduction in the grain size for 1.3 Pa deposition. The reduction of grain size was attributed to the smaller Ru grains and the enhanced

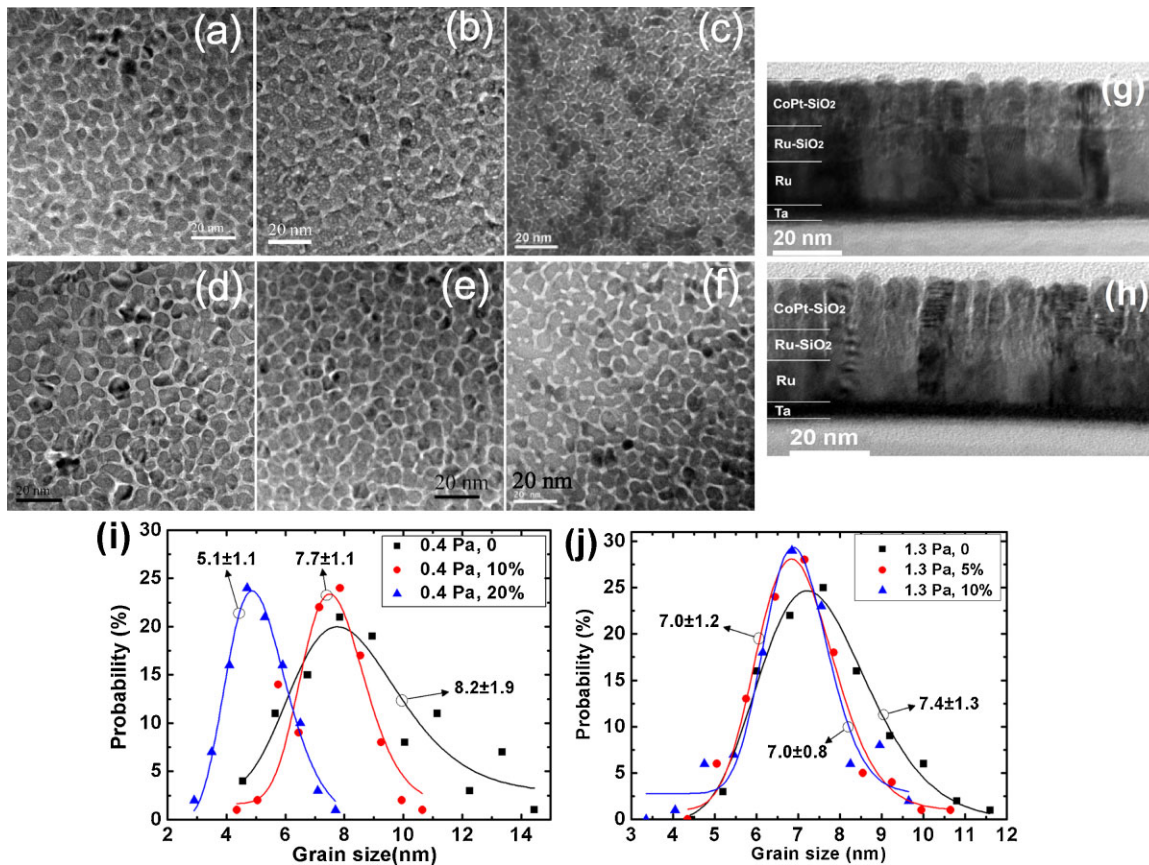


Figure 5 TEM bright field images of Co₇₂Pt₂₈-SiO₂ nanocomposite films with Ru_t deposited under different conditions. Images (a), (b), and (c) are the planar-view images with Ru_t deposited at 0.4 Pa with Ru_t layer SiO₂ content of 0%, 10 vol.% and 20 vol.%, respectively. Images (d), (e), and (f) are the planar-view images with Ru_t deposited at 1.3 Pa with Ru_t layer SiO₂ content of 0%, 5 vol.% and 10 vol.%, respectively. Images (g) and (h) are cross-section images of the samples in (b) and (f). Plot (i) and (j) are grain size distributions of Co₇₂Pt₂₈ with Ru_t deposited at 0.4 and 1.3 Pa and various SiO₂ content. The grain size was center to center distance of two neighboring grains.

oxide segregation in the initial growth region of the Co₇₂Pt₂₈ layer [18]. The average grain size of Co₇₂Pt₂₈ layer with Ru_t layer deposited at 1.3 Pa was smaller than that at 0.4 Pa when SiO₂ content was smaller than 20 vol.%. This was due to the better isolated Ru grains in the Ru_t layer deposited at 1.3 Pa than at 0.4 Pa, as shown in Figs. 3 and 5(g) and (h).

Figure 6 shows the dependence of out-of-plane hysteresis loops, coercivities (H_c) and remanence ratios ($m_R = M/M_S$) of Co₇₂Pt₂₈-SiO₂ nanocomposite films with Ru_t deposited at 0.4 and 1.3 Pa and various SiO₂ additions. For Co₇₂Pt₂₈ film with Ru_t deposited at 1.3 Pa, adding 5 vol.% SiO₂ into the Ru_t did not lead to noticeable changes in H_c . With further increasing in SiO₂ content, the H_c decreased. For Co₇₂Pt₂₈ film deposited at 0.4 Pa, adding SiO₂ into the Ru_t did not lead to appreciable changes in H_c . There was no notable change in m_R of the film until SiO₂ content was 20 vol.% for both 0.4 and 1.3 Pa deposition. When SiO₂ content was 20 vol.%, m_R reduced. The reduction of m_R could be attributed to both deteriorated texture and reduced grain size which increased the thermal demagnetization of the film. On the other hand, the Co₇₂Pt₂₈-SiO₂ film with Ru_t deposited at 1.3 Pa displayed both higher H_c and m_R than those with Ru_t

deposited at 0.4 Pa. The H_c of the film was determined by both the microstructure of the Co₇₂Pt₂₈ grains and magnetization reversal mechanism of the film. Therefore, the higher H_c and m_R at 1.3 Pa were possibly attributed to the better texture of Co₇₂Pt₂₈ at 1.3 Pa than that at 0.4 Pa as shown in Fig. 4.

4 Summary In this paper, the effects of sputter growth conditions of Ru_t underlayer on the microstructure of this layer were studied. The effects of growth conditions of the Ru_t layer on the microstructure and magnetic properties of Co₇₂Pt₂₈-SiO₂ top layer were further investigated. Results showed that both the SiO₂ content and the deposition conditions (pressure and power) affected the Ru underlayer texture greatly. Increasing SiO₂ content in the Ru_t layer deteriorated slightly the texture of Ru grains in this layer generally. Although the low-pressure (0.4 Pa) deposition could produce a better texture of Ru than high-pressure (1.3 Pa) deposition without SiO₂ addition, high-pressure deposition could better protect the texture of Ru than low-pressure deposition with SiO₂ addition. Furthermore, the high-pressure deposition of Ru_t layer at low SiO₂ content

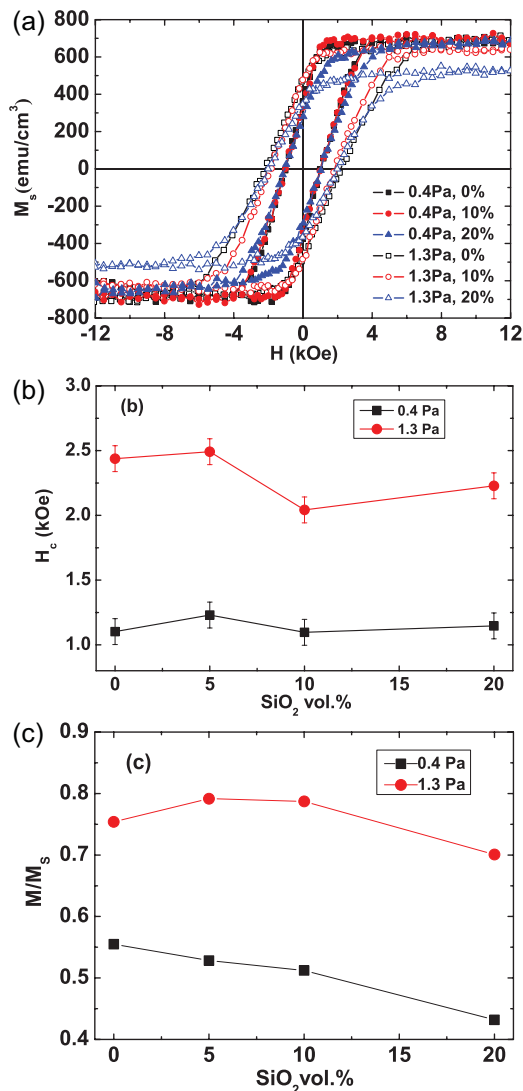


Figure 6 Plot (a) was the out-of-plane hysteresis loops of $\text{Co}_{72}\text{Pt}_{28}$ - SiO_2 nanocomposite films Ru_t deposited at 0.4 Pa and 1.3 Pa and various SiO_2 additions (0%, 10 vol.% and 20 vol.%). The deposition power of Ru_t layer was 50 W. Plots (b) and (c) are coercivity and remanence ratio of the films as a function of V_{SiO_2} in the Ru_t . The error bars represented the standard error of the mean. The lines were only used to guide the readers' eyes.

produced better texture of $\text{Co}_{72}\text{Pt}_{28}$ grains grown on it than low pressure. The sizes of the Ru grains and $\text{Co}_{72}\text{Pt}_{28}$ grains decreased from 6.7 ± 0.9 to 5.3 ± 1.3 nm and from 8.2 ± 1.9 to 5.1 ± 1.1 nm with the addition of SiO_2 up to 20 vol.%, respectively. A high-pressure deposition of Ru_t layer further reduced the grain size of $\text{Co}_{72}\text{Pt}_{28}$ due to the porosity in the grain boundary regions of the Ru_t layer. Adding 5 vol.% SiO_2 into the Ru_t did not lead to noticeable changes in the coercivity and remanence ratio of the $\text{Co}_{72}\text{Pt}_{28}$ layer. Further increasing SiO_2 content in Ru_t layer led to the decrease of both the coercivity and the remanence ratio of $\text{Co}_{72}\text{Pt}_{28}$ layer. A high-pressure deposition of Ru_t layer resulted in a

higher coercivity and remanence ratio of the $\text{Co}_{72}\text{Pt}_{28}$ layer than those with low-pressure depositions. The above results suggested that the high-pressure deposition with a small amount of SiO_2 addition could reduce the grain size of the Ru_t layer and hence, the $\text{Co}_{72}\text{Pt}_{28}$ layer without adversely affecting the magnetic properties of the $\text{Co}_{72}\text{Pt}_{28}$ layer.

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References

- [1] S. D. Bader, *Rev. Mod. Phys.* **78**, 1 (2006).
- [2] S. Iwasaki, *IEEE Trans. Magn.* **20**, 657 (1984).
- [3] M. Zheng, B. R. Acharya, G. Choe, J. N. Zhou, Z. D. Yang, E. N. Abarra, and K. E. Johnson, *IEEE Trans. Magn.* **40**, 2498 (2004).
- [4] Y. Inaba, T. Shimatsu, T. Oikawa, H. Sato, H. Aoi, H. Muraoka, and Y. Nakamura, *IEEE Trans. Magn.* **40**, 2486 (2004).
- [5] S. N. Piramanayagam, C. K. Pock, L. Li, C. Y. Ong, C. S. Mah, and J. Z. Shi, *Appl. Phys. Lett.* **89**, 162504 (2006).
- [6] S. N. Piramanayagam, J. Z. Shi, H. B. Zhao, C. K. Pock, C. S. Mah, C. Y. Ong, J. M. Zhao, J. Zhang, Y. S. Kay, and L. Lu, *IEEE Trans. Magn.* **43**, 633 (2007).
- [7] H. Yuan, Y. L. Qin, and D. E. Laughlin, *Thin Solid Films* **517**, 990 (2008).
- [8] H. Yuan and D. E. Laughlin, *Appl. Phys. Lett.* **93**, 102511 (2008).
- [9] H. Yuan and D. E. Laughlin, *J. Appl. Phys.* **105**, 07B707 (2009).
- [10] H. Yuan, D. E. Laughlin, X. Zhu, and B. Lu, *J. Appl. Phys.* **103**, 07F513 (2008).
- [11] K. K. M. Pandey, J. S. Chen, B. C. Lim, and G. M. Chow, *J. Appl. Phys.* **104**, 073904 (2008).
- [12] S. Yonemura, S. Saito, A. Hashimoto, and M. Takahashi, *J. Magn. Magn. Mater.* **320**, 3053 (2008).
- [13] B. D. Cullity, *Elements of X-Ray Diffraction*, second ed. (Addison-Wesley Publ. Co., Inc., Reading, Massachusetts, 1978), p. 488.
- [14] G. Bauer and W. Richter, *Optical Characterization of Epitaxial Semiconductor Layers*, first ed. (Springer, Berlin, 1996), p. 289.
- [15] E. McCarthy, R. T. Rajendra Kumar, B. Dogget, S. Chakrabarti, R. J. O'Haire, S. B. Newcomb, J.-P. Mosnier, M. O. Henry, and E. McGlynn, *J. Phys. D: Appl. Phys.* **44**, 375401 (2011).
- [16] M. D. Vaudin, *J. Res. Natl. Inst. Stand. Technol.* **106**, 1063 (2001).
- [17] J. A. Thornton, *J. Vac. Sci. Technol. A* **4**, 3095 (1986).
- [18] I. Takekuma, R. Araki, M. Igarashi, H. Nemoto, I. Tamai, Y. Hirayama, and Y. Hosoe, *J. Appl. Phys.* **99**, 08E713 (2006).